

ABSTRACT

A wafer polishing system, comprising: a front-end module (1); a wafer polishing unit (2), comprising a polishing transmission mechanism (21); a wafer cleaning unit (3); and a wafer transmission channel (4) extending at least on the wafer cleaning unit (3). The front-end module (1), the wafer cleaning unit (3), and the wafer polishing unit (2) are sequentially arranged adjacent to each other; a first transfer station (51), a second transfer station (52), a third transfer station (53), a first transmission device (61), and a second transmission device (62) are provided in the wafer transmission channel (4); the first transmission device (61) is used for implementing wafer transmission between the first transfer station (51) and the second transfer station (52); the second transmission device (62) is used for implementing wafer transmission between the second transfer station (52) and the third transfer station (53); and the third transfer station (53) is further used for wafer transmission and transferring between the wafer cleaning unit (3) and the wafer polishing unit (2). The wafer transmission stroke in the wafer transmission channel (4) is divided into two sections which are respectively completed by the first transmission device (61) and the second transmission device (62), such that the volume is reduced, complex actions can be carried out in a narrow space, and the transmission speed is higher; and more process possibilities can be achieved by setting different transmission forms.

FIG. 1